

MBRB20100CT

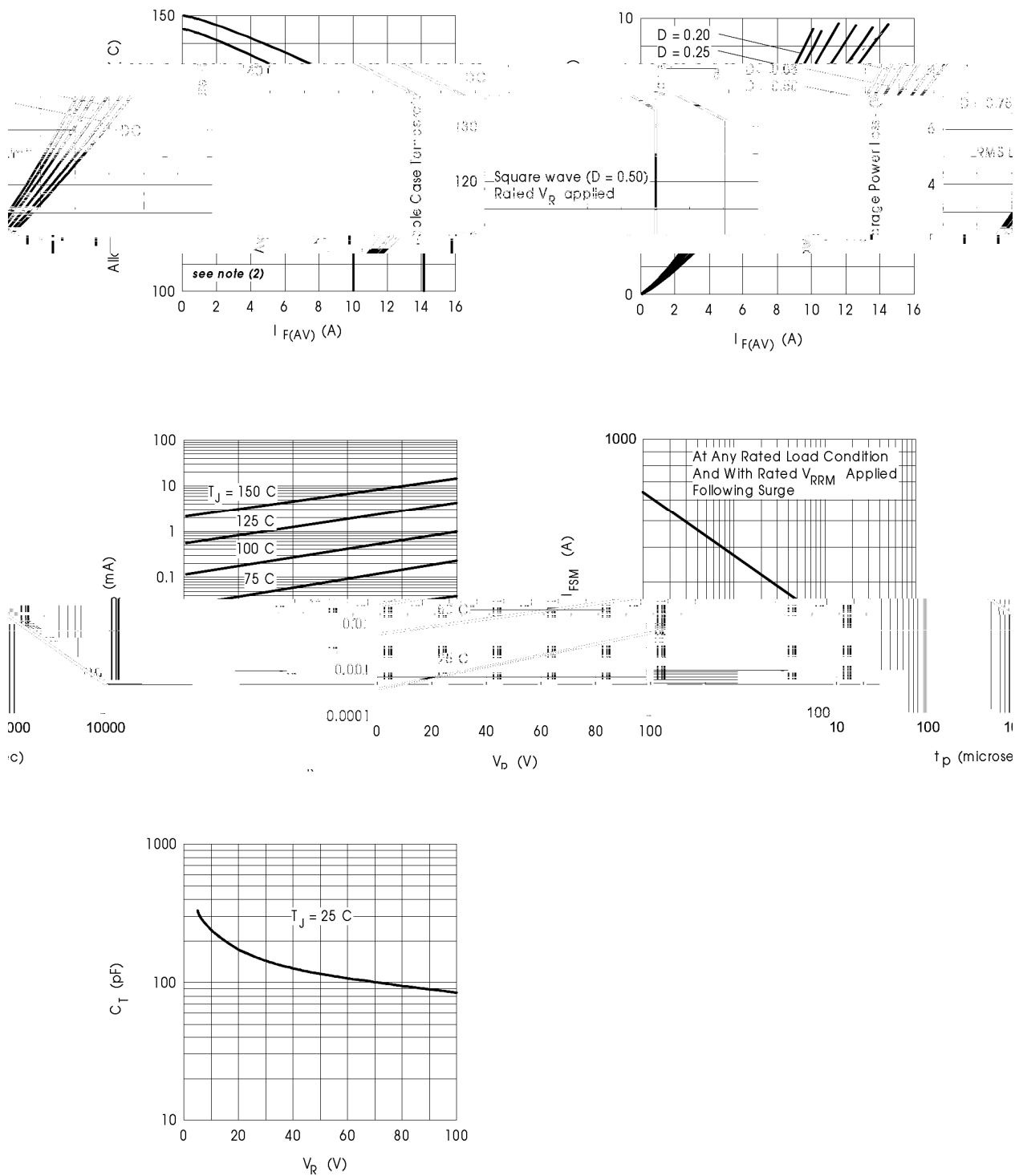
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	100	V
Working Peak Reverse Voltage	V_{RWM}	100	V
Peak Repetitive Forward Current	I_{FRM}	20	A
Average Rectified Forward Current	$I_{F(AV)}$	10	A
	$I_{F(AV)} (total)$	20	A
Non Repetitive Peak Surge Current	I_{FSM}	150	A
Peak Repetitive Reverse Surge Current	I_{RRM}	0.5	A
Thermal Resistance Junction to Case	$R_{\theta JC}$	2.0	/W
Junction Temperature Range	T_j	175	
Storage Temperature Range	T_{stg}	-55~175	

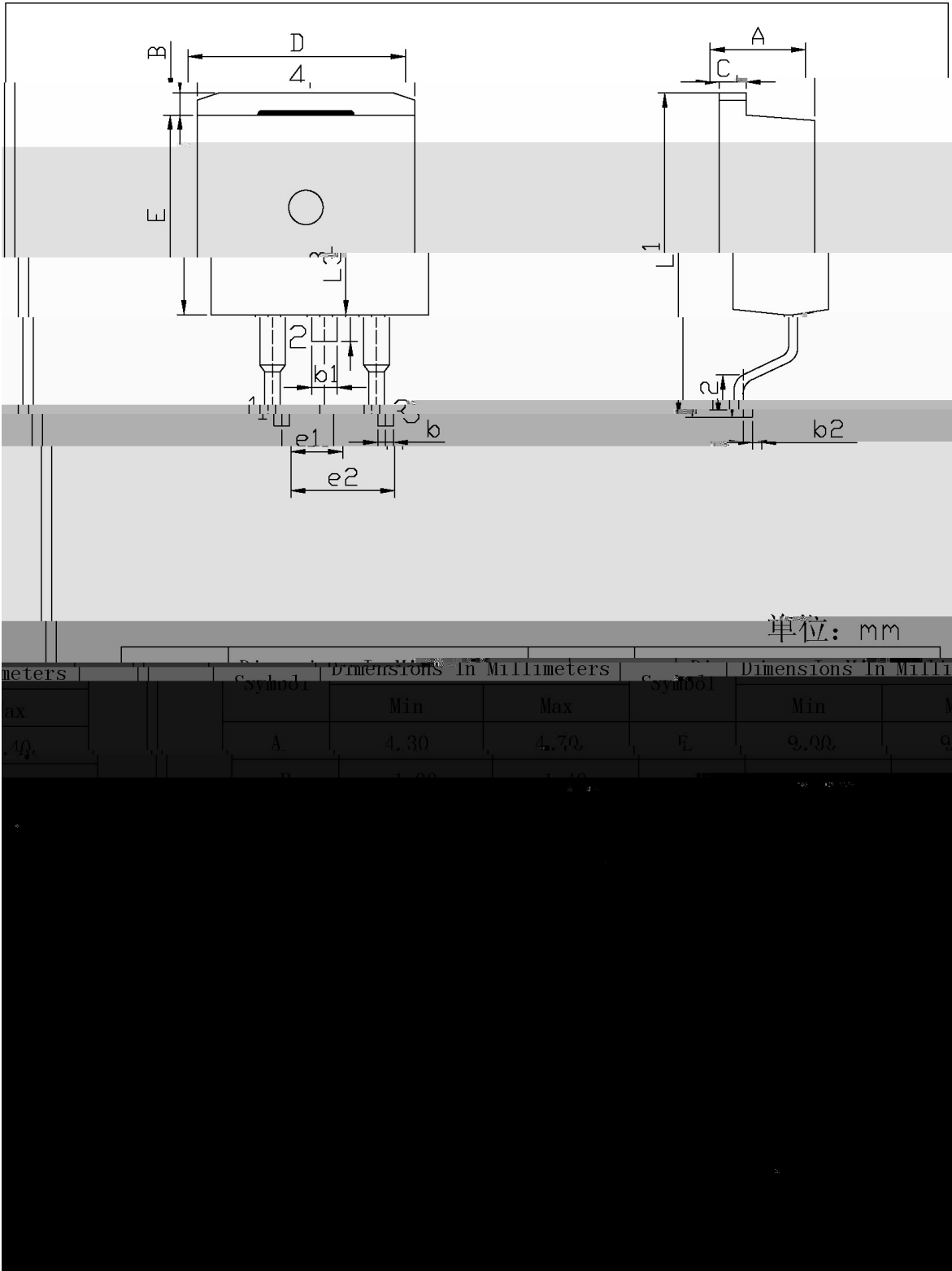
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Peak Forward Voltage	V_{FM}	$I_F=10A(T_C=25^{\circ}C)$			0.85	V
		$I_F=10A(T_C=125^{\circ}C)$			0.7	V
		$I_F=20A(T_C=25^{\circ}C)$			0.95	V
		$I_F=20A(T_C=125^{\circ}C)$			0.85	V
Instantaneous Reverse Current	I_{RM}	$V_R=100V(T_C=25^{\circ}C)$			0.15	mA
		$V_R=100V(T_C=125^{\circ}C)$			150	mA
Voltage Rate of Change	dv/dt				10000	V/ μs

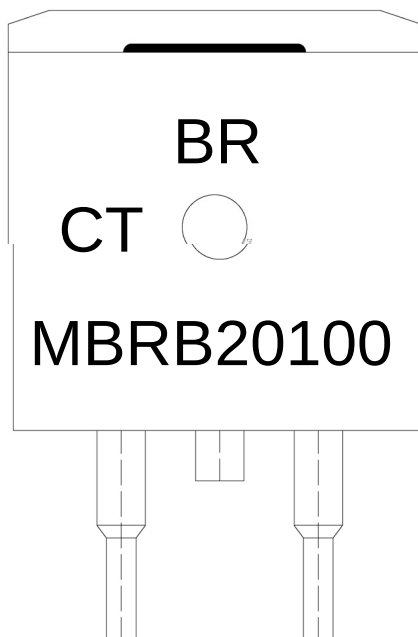
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



BR

MBRB20100

CT:

Note:

BR:

Company Code

MBRB20100

Product Type Code

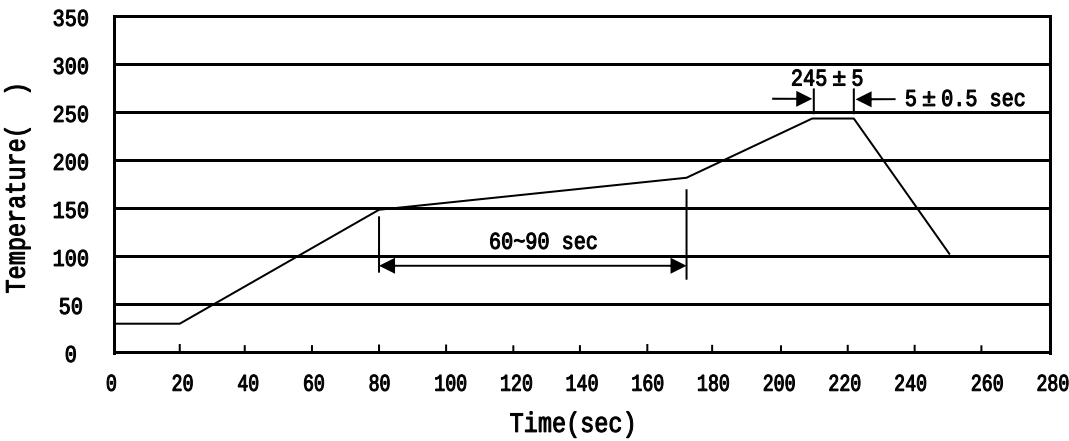
CT:

Internal Structure

****:

Lot No. Code, code change with Lot No.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 °C , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 °C , Duration:5±0.5sec.
- 3

2 10

/sec.

3. Cooling Speed: 2~10 °C /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
TO-263	800	1	800	6	4,800	13" ×24	360×360×50	380×335×366

/ TUBE

Package Type	Units					Dimension (unit mm ³)		
TO-263	50	20	1,000	5	5,000	532×33×7.0	555×164×50	575×290×180

/ Notices